

**SLOVENSKI STANDARD**  
**SIST-TP CLC/TR 62258-4:2013**  
**01-marec-2013**

---

**Izdelki s polprevodniškimi čipi - 4. del: Vprašalnik za uporabnike in dobavitelje čipov**

Semiconductor die products - Part 4: Questionnaire for die users and suppliers

Halbleiter-Chip-Erzeugnisse - Teil 4: Fragebogen für Chip-Anwender und -Lieferanten

Produits de puces de semiconducteurs - Partie 4: Questionnaire destiné aux utilisateurs et fournisseurs de puces

**ITeH STANDARD PREVIEW**  
**(standards.iteh.ai)**

**Ta slovenski standard je istoveten z: CLC/TR 62258-4:2013**

SIST-TP CLC/TR 62258-4:2013  
<https://standards.iteh.ai/catalog/standards/sist/5caci645-7f19-45c6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013>

---

**ICS:**

31.080.99	Drugi polprevodniški elementi	Other semiconductor devices
31.200	Integrirana vezja, mikroelektronika	Integrated circuits. Microelectronics

**SIST-TP CLC/TR 62258-4:2013**

**en**

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

[SIST-TP CLC/TR 62258-4:2013](#)

<https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013>

TECHNICAL REPORT  
RAPPORT TECHNIQUE  
TECHNISCHER BERICHT

**CLC/TR 62258-4**

January 2013

ICS 31.080.99

Supersedes CLC/TR 62258-4:2007

English version

**Semiconductor die products -  
Part 4: Questionnaire for die users and suppliers  
(IEC/TR 62258-4:2012)**

Produits de puces de semiconducteurs -  
Partie 4: Questionnaire destiné  
aux utilisateurs et fournisseurs de puces  
(CEI/TR 62258-4:2012)

Halbleiter-Chip-Erzeugnisse -  
Teil 4: Fragebogen für Chip-Anwender  
und -Lieferanten  
(IEC/TR 62258-4:2012)

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

This Technical Report was approved by CENELEC on 2012-09-12.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Management Centre: Avenue Marnix 17, B - 1000 Brussels**

## Foreword

The text of document 47/2073A/DTR, future edition 2 of IEC/TR 62258-4, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as CLC/TR 62258-4:2013.

This document supersedes CLC/TR 62258-4:2007.

CLC/TR 62258-4:2013 includes the following significant technical changes with respect to CLC/TR 62258-4:2007:

The document checklist was changed to mirror EN 62258-1:2010 requirements exactly.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC [and/or CEN] shall not be held responsible for identifying any or all such patent rights.

## Endorsement notice

The text of the International Standard IEC/TR 62258-4:2012 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC/TR 62258-7 NOTE Harmonised as CLC/TR 62258-7.

IEC/TR 62258-8 NOTE Harmonised as CLC/TR 62258-8.

**(standards.iteh.ai)**

[SIST-TP CLC/TR 62258-4:2013](https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013)

<https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013>

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050	Series	International Electrotechnical Vocabulary (IEV)	-	-
IEC 62258-1	2009	Semiconductor die products - Part 1: Procurement and use	EN 62258-1	2010
IEC 62258-2	2011	Semiconductor die products - Part 2: Exchange data formats	EN 62258-2	2011

## iTeh STANDARD PREVIEW (standards.iteh.ai)

[SIST-TP CLC/TR 62258-4:2013](https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013)

<https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013>

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

[SIST-TP CLC/TR 62258-4:2013](https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013)

<https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013>



# TECHNICAL REPORT

# RAPPORT TECHNIQUE

**Semiconductor die products –  
Part 4: Questionnaire for die users and suppliers**

**Produits de puces de semiconducteurs –  
Partie 4: Questionnaire destiné aux utilisateurs et fournisseurs de puces**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

COMMISSION  
ELECTROTECHNIQUE  
INTERNATIONALE

PRICE CODE  
CODE PRIX

R

ICS 31.080.99

ISBN 978-2-83220-297-5

**Warning! Make sure that you obtained this publication from an authorized distributor.  
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

## CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references .....	6
3 Terms and definitions .....	6
4 General .....	6
5 Data exchange .....	7
Annex A (normative) Customer questionnaire on die devices .....	8
Bibliography.....	18
Table A.1 – Basic data.....	9
Table A.2 – Bare die and wafers .....	10
Table A.3 – Die and wafers with connection structures .....	11
Table A.4 – Minimally-packaged die devices.....	12
Table A.5 – Quality, reliability and storage.....	12
Table A.6 – Terminal data.....	14
Table A.7 – Terminal geometries.....	14
Table A.8 – Polygon vertices .....	15
Table A.9 – Fiducial definitions.....	15
Table A.10 – Fiducial positions.....	16
Table A.11 – Simulator data.....	16
Table A.12 – Group definitions.....	17
Table A.13 – Permutations.....	17



## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## SEMICONDUCTOR DIE PRODUCTS –

## Part 4: Questionnaire for die users and suppliers

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62258-4, which is a technical report, has been prepared by IEC technical committee 47: Semiconductor devices.

This technical report contains attached files in the form of [47-62258-4-TR-E-worksheet.xls](#). These files are intended to be used as a complement and do not form an integral part of the technical report.

This second edition cancels and replaces the first edition published in 2007 and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

The document checklist was changed to mirror IEC 62258-1:2009 requirements exactly.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
47/2073A/DTR	47/2108/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62258 series, published under the general title *Semiconductor die products*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

[SIST-TP CLC/TR 62258-4:2013](https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013)

<https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013>

## INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework Project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organizations that helped prepare this document included the ESPRIT ENCAST and ENCASIT projects, the Die Products Consortium, JEITA, JEDEC and ZVEI.

## **iTeh STANDARD PREVIEW** **(standards.iteh.ai)**

[SIST-TP CLC/TR 62258-4:2013](https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013)

<https://standards.iteh.ai/catalog/standards/sist/3cacf845-7f19-45e6-bc98-b224d75213f8/sist-tp-clc-tr-62258-4-2013>